SB2100 2.0AMPS. SCHOTTKY BARRIER RECTIFIERS

FEATURE

- . High current capability
- . Low forward voltage drop
- . Low power loss, high efficiency
- . High surge capability
- . High temperature soldering guaranteed 260°C /10sec/ 0.375" lead length at 5 lbs tension

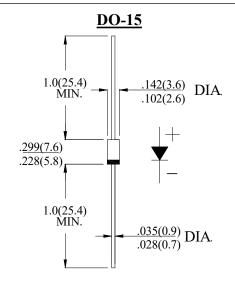
MECHANICAL DATA

. Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C

. Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy

. Polarity: color band denotes cathode

. Mounting position: any



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at $25\,^{\circ}\mathrm{C}$ ambient temperature unless otherwise specified.

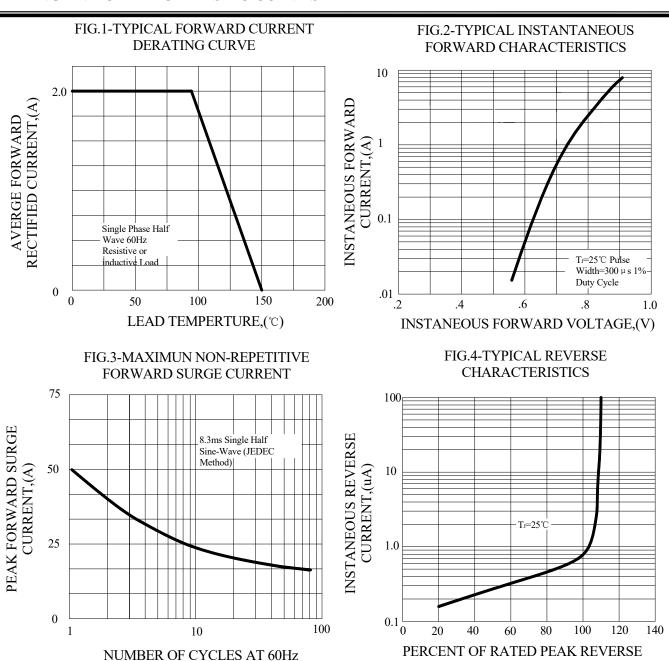
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	SYM	SB2100	units
Type Ivalliber	BOL	302100	
Maximum Recurrent Peak Reverse Voltage	$V_{ m RRM}$	100	V
Maximum RMS Voltage	$V_{ m RMS}$	70	V
Maximum DC blocking Voltage	$V_{ m DC}$	100	V
Maximum Average Forward Rectified Current	I	2.0	A
.375"(9.5mm) lead length	$I_{\text{F(AV)}}$	2.0	
Peak Forward Surge Current 8.3ms single half			
sine-wave superimposed on rated load (JEDEC	I_{FSM}	50.0	A
method)			
Maximum Forward Voltage at 2.0A DC	$V_{ m F}$	0.85	V
Maximum DC Reverse Current @T _J =25°C	,	0.1	mA
at rated DC blocking voltage @T _J =100°C	I_{R}	10.0	
Typical Junction Capacitance (Note 1)	$C_{ m J}$	65	pF
Typical Thermal Resistance (Note 2)	$R_{(JA)}$	70	°C/W
Storage Temperature	T _{STG}	-55 to +150	°C
Operation Junction Temperature	$T_{ m J}$	-55 to +150	°C

Note:

- 1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
- 2. Thermal Resistance from Junction to Ambient at 0.375" (9.5mm) lead length, vertical P.C.Board Mounted.

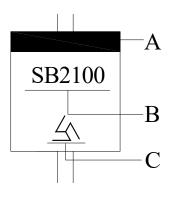
RATING AND CHARACTERISTIC CURVES



VOLTAGE,(%)

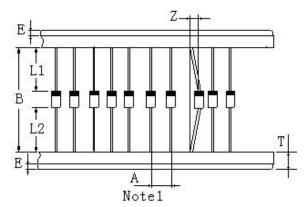
Marking and packaging illustration

1. Marking



SYMBOL	Explanation
A	Color Band Denotes Cathode
В	Product Name
C	Trademark

2. Packaging



ITEM	SYMBOL	SPECIFICATIONS	SPECIFICATIONS
		(mm)	(inch)
Component alignment	Z	1.2max	0.048max
Tape width	T	6.0±0.4	0.2±0.016
Exposed adhesive	Е	0.8max	0.032max
Body eccentricity	L1-L2	1.0max	0.040max
Component	A	5.0±0.5	0.2±0.02
Inner tap	В	52.0~53.5	2.06~2.11

NOTE:

Each component lead shall be sandwiched between tapes for a minimum of 2.5mm (0.1inch)